

M5M416160BJ,TP,RT-6,-7,-8,-6S,-7S,-8S

FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

DESCRIPTION

This is a family of 1048576-word by 16-bit dynamic RAMS, fabricated with the high performance CMOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential.

The use of double-layer aluminum process combined with triple-well CMOS technology and a single-transistor dynamic storage stacked capacitor cell provide high circuit density at reduced costs. Multiplexed address inputs permit both a reduction in pins and an increase in system densities.

FEATURES

Type name	RAS access time (max.ns)	CAS access time (max.ns)	Address access time (max.ns)	OE access time (max.ns)	Cycle time (min.ns)	Power dissipation (typ.mW)
M5M416160BXX-6,-6S	60	15	30	15	110	430
M5M416160BXX-7,-7S	70	20	35	20	130	385
M5M416160BXX-8,-8S	80	20	40	20	150	340

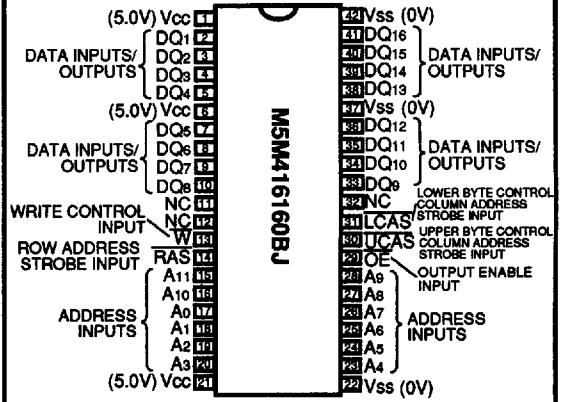
XX=J,TP,RT

- Standard 42pin SOJ, 50pin TSOP
- Single 5.0V ± 10% supply
- Low stand-by power dissipation
5.5mW (Max) CMOS Input level
- Low operating power dissipation
M5M416160Bxx-6,-6S 530.0mW (Max)
M5M416160Bxx-7,-7S 470.0mW (Max)
M5M416160Bxx-8,-8S 420.0mW (Max)
- Fast-page mode, Read-modify-write, RAS-only refresh, CAS before RAS refresh, Hidden refresh capabilities
- Early-write mode and OE to control output buffer impedance
- All inputs, output TTL compatible and low capacitance
- 4096 refresh cycles every 64ms (A0 ~A11)

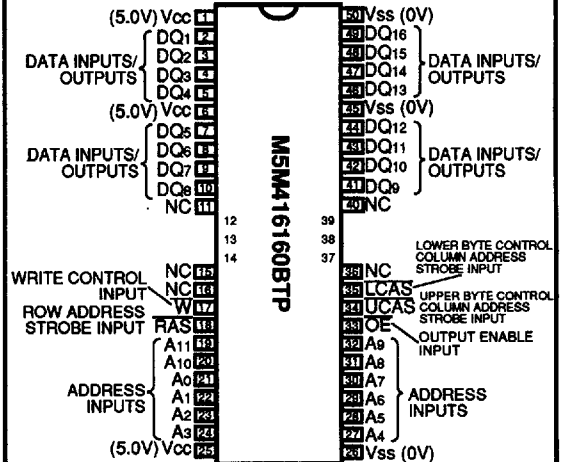
APPLICATION

Main memory unit for computers, Microcomputer memory, Refresh memory for CRT

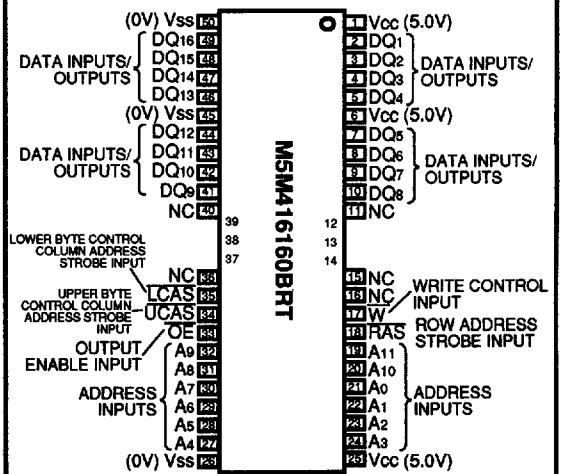
PIN CONFIGURATION (TOP VIEW)



Outline 42P0K(400mil SOJ)



Outline 50P3W-L(400mil TSOP)



Outline 50P3W-M(400mil TSOP)

NC : NO CONNECTION

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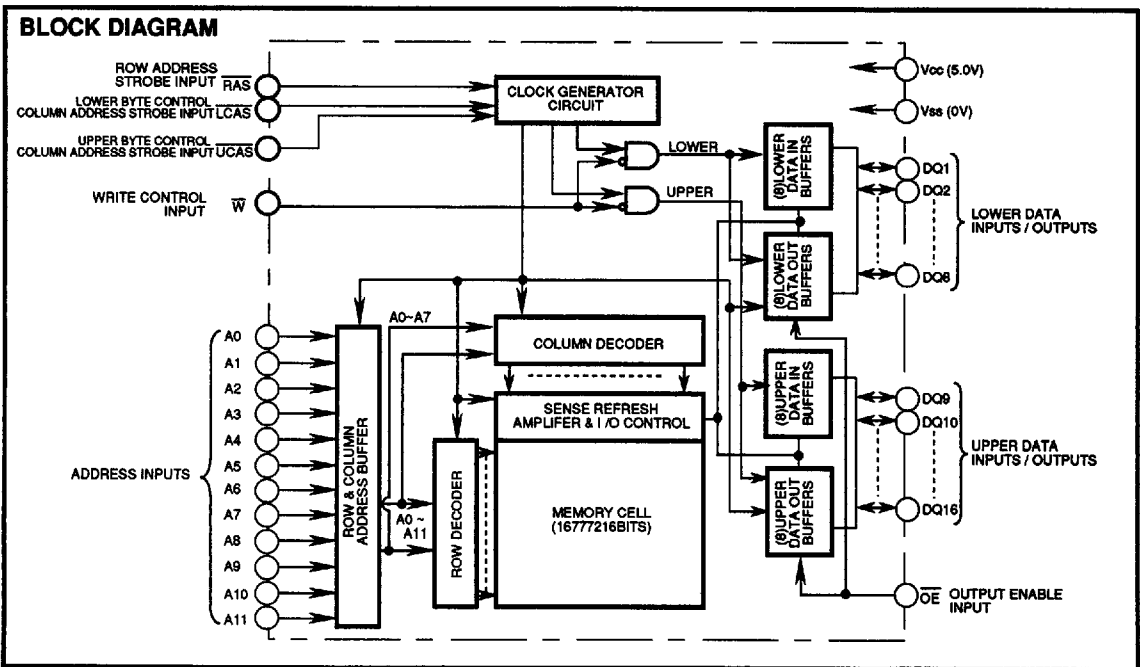
FUNCTION

The M5M416160BJ, TP, RT provide, in addition to normal read, write, and read-modify-write operations, a number of other functions, e.g., fast page mode, $\overline{\text{RAS}}$ -only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs					Input/Output	
	RAS	LCAS	UCAS	$\overline{\text{W}}$	$\overline{\text{OE}}$	DQ1-DQ8	DQ9-DQ16
Lower byte Read	ACT	ACT	NAC	NAC	ACT	DOUT	OPN
Upper byte Read	ACT	NAC	ACT	NAC	ACT	OPN	DOUT
Word Read	ACT	ACT	ACT	NAC	ACT	DOUT	DOUT
Lower Byte Write	ACT	ACT	NAC	ACT	NAC	DIN	DNC
Upper Byte Write	ACT	NAC	ACT	ACT	NAC	DNC	DIN
Word write	ACT	ACT	ACT	ACT	NAC	DIN	DIN
$\overline{\text{RAS}}$ -only refresh	ACT	NAC	NAC	DNC	DNC	OPN	OPN
Hidden refresh	ACT	ACT	ACT	NAC	ACT	DOUT	DOUT
CAS before $\overline{\text{RAS}}$ refresh	ACT	ACT	ACT	DNC	DNC	OPN	OPN
Stand-by	NAC	DNC	DNC	DNC	DNC	OPN	OPN

Note : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, IVD : invalid, APD : applied, OPN : open



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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{cc}	Supply voltage	With respect to V _{ss}	-1~7	V
V _I	Input voltage		-1~7	V
V _o	Output voltage		-1~7	V
I _o	Output current		50	mA
P _d	Power dissipation	T _a =25°C	1000	mW
T _{opr}	Operating temperature		0 ~ 70	°C
T _{stg}	Storage temperature		-65 ~ 150	°C

RECOMMENDED OPERATING CONDITIONS (T_a=0~70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{cc}	Supply voltage	4.5	5.0	5.5	V
V _{ss}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.0	V
V _{IL}	Low-level input voltage, all inputs	-1		0.8	V

Note 1 : All voltage values are with respect to V_{ss}.

ELECTRICAL CHARACTERISTICS (T_a=0~70°C, V_{cc}=5.0V ± 10%, V_{ss}=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit	
			Min	Typ	Max		
V _{OH}	High-level output voltage	I _{OH} =-5mA	2.4		V _{cc}	V	
V _{OL}	Low-level output voltage	I _{OL} =4.2mA	0		0.4	V	
I _{oz}	Off-state output current	Q floating, 0V ≤ V _{out} ≤ 5.5V	-10		10	μA	
I _I	Input current	0V ≤ V _{in} ≤ 6V, Other inputs pins=0V	-10		10	μA	
I _{cc1} (AV)	Average supply current from V _{cc} operating (Note 3,4,5)	M5M416160B-6,-6S	RAS, CAS cycling t _{rc} =t _{wc} =min. output open			95	mA
		M5M416160B-7,-7S				85	
		M5M416160B-8,-8S				75	
I _{cc2}	Supply current from V _{cc} , stand-by (Note 6)	RAS = $\overline{\text{CAS}}$ = V _{IH} , output open				2	mA
		RAS = $\overline{\text{CAS}}$ ≥ V _{cc} - 0.2V				0.5	
I _{cc3} (AV)	Average supply current from V _{cc} refreshing (Note 3,5)	M5M416160B-6,-6S	RAS cycling, $\overline{\text{CAS}}$ = V _{IH} t _{rc} =min. output open			95	mA
		M5M416160B-7,-7S				85	
		M5M416160B-8,-8S				75	
I _{cc4} (AV)	Average supply current from V _{cc} Fast-Page-Mode (Note 3,4,5)	M5M416160B-6,-6S	RAS = V _{IL} , $\overline{\text{CAS}}$ cycling t _{rc} =min. output open			70	mA
		M5M416160B-7,-7S				60	
		M5M416160B-8,-8S				50	
I _{cc8} (AV)	Average supply current from V _{cc} CAS before RAS refresh mode (Note 3)	M5M416160B-6,-6S	CAS before RAS refresh cycling t _{rc} =min. output open			95	mA
		M5M416160B-7,-7S				85	
		M5M416160B-8,-8S				75	

Note 2: Current flowing into an IC is positive, out is negative.

3: I_{cc1} (AV), I_{cc3} (AV) and I_{cc4} (AV) are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.

4: I_{cc1} (AV) and I_{cc4} (AV) are dependent on output loading. Specified values are obtained with the output open.

5: Column Address can be changed once or less while RAS = V_{IL} and LCAS/UCAS = V_{IH}.

CAPACITANCE (T_a=0~70°C, V_{cc}=5.0V ± 10%, V_{ss}=0V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _i (A)	Input capacitance, address inputs	V _i =V _{ss} f=1MHz V _i =25mVrms			5	pF
C _i (OE)	Input capacitance, OE input				7	pF
C _i ($\overline{\text{W}}$)	Input capacitance, $\overline{\text{W}}$ input				7	pF
C _i (RAS)	Input capacitance, RAS input				7	pF
C _i (CAS)	Input capacitance, CAS input				7	pF
C _{i/o}	Input/Output capacitance, data ports				8	pF

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SWITCHING CHARACTERISTICS (Ta=0~70°C, Vcc=5.0V ± 10%, Vss=0V, unless otherwise noted, see notes 6,13,14)

Symbol	Parameter	Limits						Unit
		M5M416160B-6,-6S		M5M416160B-7,-7S		M5M416160B-8,-8S		
		Min	Max	Min	Max	Min	Max	
tCAC	Access time from CAS (Note7,8)		15		20		20	ns
tRAC	Access time from RAS (Note7,9)		60		70		80	ns
tAA	Column address access time (Note 7,10)		30		35		40	ns
tCPA	Access time from CAS precharge (Note 7,11)		35		40		45	ns
tOEA	Access time from OE (Note 7)		15		20		20	ns
tCLZ	Output low impedance time from CAS low (Note 7)	5		5		5		ns
tOFF	Output disable time after CAS high (Note 12)	0	15	0	15	0	15	ns
tOEZ	Output disable time after OE high (Note 12)	0	15	0	15	0	15	ns

Note 6: An initial pause of 500 μs is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS clock such as RAS-Only refresh).

Note the RAS may be cycled during the initial pause. And any 8 RAS or RAS/CAS cycles are required after prolonged periods (greater than 64 ms) of RAS inactivity before proper device operation is achieved.

7: Measured with a load circuit equivalent to 2TTL loads and 100pF.

8: Assumes that $t_{RC} \geq t_{RC(max)}$ and $t_{ASC} \geq t_{ASC(max)}$

9: Assumes that $t_{RC} \leq t_{RC(max)}$ and $t_{RAD} \leq t_{RAD(max)}$. If t_{RC} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by amount that t_{RC} exceeds the value shown.

10: Assumes that $t_{RAD} \geq t_{RAD(max)}$ and $t_{ASC} \leq t_{ASC(max)}$.

11: Assumes that $t_{CP} \leq t_{CP(max)}$ and $t_{ASC} \geq t_{ASC(max)}$

12: $t_{OFF(max)}$ and $t_{OEZ(max)}$ defines the time at which the output achieves the high impedance state ($I_{out} \leq \pm 10 \mu A$) and is not reference to $V_{OH(min)}$ or $V_{OL(max)}$.

TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write, Refresh, and Fast-Page Mode Cycles)

(Ta=0 ~ 70°C, Vcc=5.0V ± 10%, Vss=0V, unless otherwise noted, see notes 13,14)

Symbol	Parameter	Limits						Unit
		M5M416160B-6,-6S		M5M416160B-7,-7S		M5M416160B-8,-8S		
		Min	Max	Min	Max	Min	Max	
tREF	Refresh cycle time		64		64		64	ms
tRP	RAS high pulse width	40		50		60		ns
tRCD	Delay time, RAS low to CAS low (Note15)	20	45	20	50	20	60	ns
tCRP	Delay time, CAS high to RAS low	10		10		10		ns
tRPC	Delay time, RAS high to CAS low	0		0		0		ns
tCPN	CAS high pulse width	10		10		10		ns
tRAD	Column address delay time from RAS low (Note16)	15	30	15	35	15	40	ns
tASR	Row address setup time before RAS low	0		0		0		ns
tASC	Column address setup time before CAS low (Note17)	0	10	0	10	0	10	ns
tRAH	Row address hold time after RAS low	10		10		10		ns
tCAH	Column address hold time after CAS low	15		15		15		ns
tDZC	Delay time, data to CAS low (Note18)	0		0		0		ns
tDZO	Delay time, data to OE low (Note18)	0		0		0		ns
tCDD	Delay time, CAS high to data (Note19)	15		15		15		ns
tODD	Delay time, OE high to data (Note19)	15		15		15		ns
t _r	Transition time (Note20)	1	50	1	50	1	50	ns

Note 13: The timing requirements are assumed $t_r = 5ns$.

14: $V_{IH(min)}$ and $V_{IL(max)}$ are reference levels for measuring timing of input signals.

15: $t_{RC(max)}$ is specified as a reference point only. If t_{RC} is less than $t_{RC(max)}$, access time is t_{RAC} . If t_{RC} is greater than $t_{RC(max)}$, access time is controlled exclusively by t_{CAC} or t_{AA} . $t_{RC(min)}$ is specified as $t_{RC(min)} = t_{RAH(min)} + 2t_r + t_{ASC(min)}$.

16: $t_{RAD(max)}$ is specified as a reference point only. If $t_{RAD} \geq t_{RAD(max)}$ and $t_{ASC} \leq t_{ASC(max)}$, access time is controlled exclusively by t_{AA} .

17: $t_{ASC(max)}$ is specified as a reference point only. If $t_{RC} \geq t_{RC(max)}$ and $t_{ASC} \geq t_{ASC(max)}$, access time is controlled exclusively by t_{CAC} .

18: Either t_{DZC} or t_{DZO} must be satisfied.

19: Either t_{CDD} or t_{ODD} must be satisfied.

20: t_r is measured between $V_{IH(min)}$ and $V_{IL(max)}$.

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Read and Refresh Cycles

Symbol	Parameter	Limits						Unit
		M5M416160B-6,-6S		M5M416160B-7,-7S		M5M416160B-8,-8S		
		Min	Max	Min	Max	Min	Max	
tRC	Read cycle time	110		130		150		ns
tRAS	RAS low pulse width	60	10000	70	10000	80	10000	ns
tCAS	CAS low pulse width	15	10000	20	10000	20	10000	ns
tCSH	CAS hold time after RAS low	60		70		80		ns
tRSH	RAS hold time after CAS low	15		20		20		ns
tRCS	Read Setup time after CAS high	0		0		0		ns
tRCH	Read hold time after CAS low (Note 21)	0		0		0		ns
tRRH	Read hold time after RAS low (Note 21)	10		10		10		ns
tRAL	Column address to RAS hold time	30		35		40		ns
tOCH	CAS hold time after OE low	15		20		20		ns
tORH	RAS hold time after OE low	15		20		20		ns

Note 21: Either tRCH or tRRH must be satisfied for a read cycle.

Write Cycle (Early Write and Delayed Write)

Symbol	Parameter	Limits						Unit
		M5M416160B-6,-6S		M5M416160B-7,-7S		M5M416160B-8,-8S		
		Min	Max	Min	Max	Min	Max	
tWC	Write cycle time	110		130		150		ns
tRAS	RAS low pulse width	60	10000	70	10000	80	10000	ns
tCAS	CAS low pulse width	15	10000	20	10000	20	10000	ns
tCSH	CAS hold time after RAS low	60		70		80		ns
tRSH	RAS hold time after CAS low	15		20		20		ns
tWCS	Write setup time before CAS low (Note 23)	0		0		0		ns
tWCH	Write hold time after CAS low	10		10		15		ns
tCWL	CAS hold time after W low	15		20		20		ns
tRWL	RAS hold time after W low	15		20		20		ns
tWP	Write pulse width	10		10		15		ns
tDS	Data setup time before CAS low or W low	0		0		0		ns
tDH	Data hold time after CAS low or W low	10		15		15		ns
tOEH	OE hold time after W low	15		20		20		ns

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Read-Write and Read-Modify-Write Cycles

Symbol	Parameter	Limits						Unit
		M5M416160B-6,-6S		M5M416160B-7,-7S		M5M416160B-8,-8S		
		Min	Max	Min	Max	Min	Max	
trwc	Read write/read modify write cycle time (Note22)	155		180		200		ns
tr $\overline{\text{AS}}$	$\overline{\text{RAS}}$ low pulse width	105	10000	120	10000	130	10000	ns
tc $\overline{\text{AS}}$	$\overline{\text{CAS}}$ low pulse width	60	10000	70	10000	70	10000	ns
tcsh	$\overline{\text{CAS}}$ hold time after $\overline{\text{RAS}}$ low	105		120		130		ns
trsh	$\overline{\text{RAS}}$ hold time after $\overline{\text{CAS}}$ low	60		70		70		ns
trcs	Read setup time before $\overline{\text{CAS}}$ low	0		0		0		ns
tcwd	Delay time, $\overline{\text{CAS}}$ low to $\overline{\text{W}}$ low (Note23)	40		45		45		ns
trwd	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{W}}$ low (Note23)	85		95		105		ns
tawd	Delay time, address to $\overline{\text{W}}$ low (Note23)	55		60		65		ns
tcwl	$\overline{\text{CAS}}$ hold time after $\overline{\text{W}}$ low	15		20		20		ns
trwl	$\overline{\text{RAS}}$ hold time after $\overline{\text{W}}$ low	15		20		20		ns
twp	Write pulse width	10		10		15		ns
tbs	Data setup time before $\overline{\text{W}}$ low	0		0		0		ns
t $\overline{\text{DH}}$	Data hold time after $\overline{\text{W}}$ low	10		15		15		ns
t $\overline{\text{OE}}$	$\overline{\text{OE}}$ hold time after $\overline{\text{W}}$ low	15		15		15		ns

Note 22: trwc is specified as trwc(min) = trcs(max) + t $\overline{\text{ODD}}$ (min) + trwl(min) + trp(min) + 5T.

23: twcs, tcwd, trwd and tawd and, t $\overline{\text{CPWD}}$ are specified as reference points only. If twcs \geq twcs(min) the cycle is an early write cycle and the DQpins will remain high impedance throughout the entire cycle. If tcwd \geq tcwd(min), trwd \geq trwd (min), tawd \geq tawd(min) and t $\overline{\text{CPWD}}$ \geq t $\overline{\text{CPWD}}$ (min) (for fast page mode cycle only), the cycle is a read-modify-write cycle and the DQ will contain the data read from the selected address. If neither of the above condition (delayed write) of the DQ (at access time and until $\overline{\text{CAS}}$ or $\overline{\text{OE}}$ goes back to V $\overline{\text{H}}$) is indeterminate.

Fast-Page Mode Cycle (Read, Early Write, Read -Write, Read-Modify-Write Cycle) (Note 24)

Symbol	Parameter	Limits						Unit
		M5M416160B-6,-6S		M5M416160B-7,-7S		M5M416160B-8,-8S		
		Min	Max	Min	Max	Min	Max	
tpc	Fast page mode read/write cycle time	40		45		50		ns
tp $\overline{\text{RWC}}$	Fast page mode read write/read modify write cycle time	85		95		105		ns
tr $\overline{\text{AS}}$	$\overline{\text{RAS}}$ low pulse width for read write cycle (Note25)	100	125000	115	125000	130	125000	ns
tcp	$\overline{\text{CAS}}$ high pulse width (Note26)	10	15	10	15	10	15	ns
t $\overline{\text{CPRH}}$	$\overline{\text{RAS}}$ hold time after $\overline{\text{CAS}}$ precharge	35		40		45		ns
t $\overline{\text{CPWD}}$	Delay time, $\overline{\text{CAS}}$ precharge to $\overline{\text{W}}$ low (Note23)	60		65		70		ns

Note 24: All previously specified timing requirements and switching characteristics are applicable to their respective fast page mode cycle.

25: tr $\overline{\text{AS}}$ (min) is specified as two cycles of $\overline{\text{CAS}}$ input are performed.

26: tcp(max) is specified as a reference point only.

$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh Cycle (Note 27)

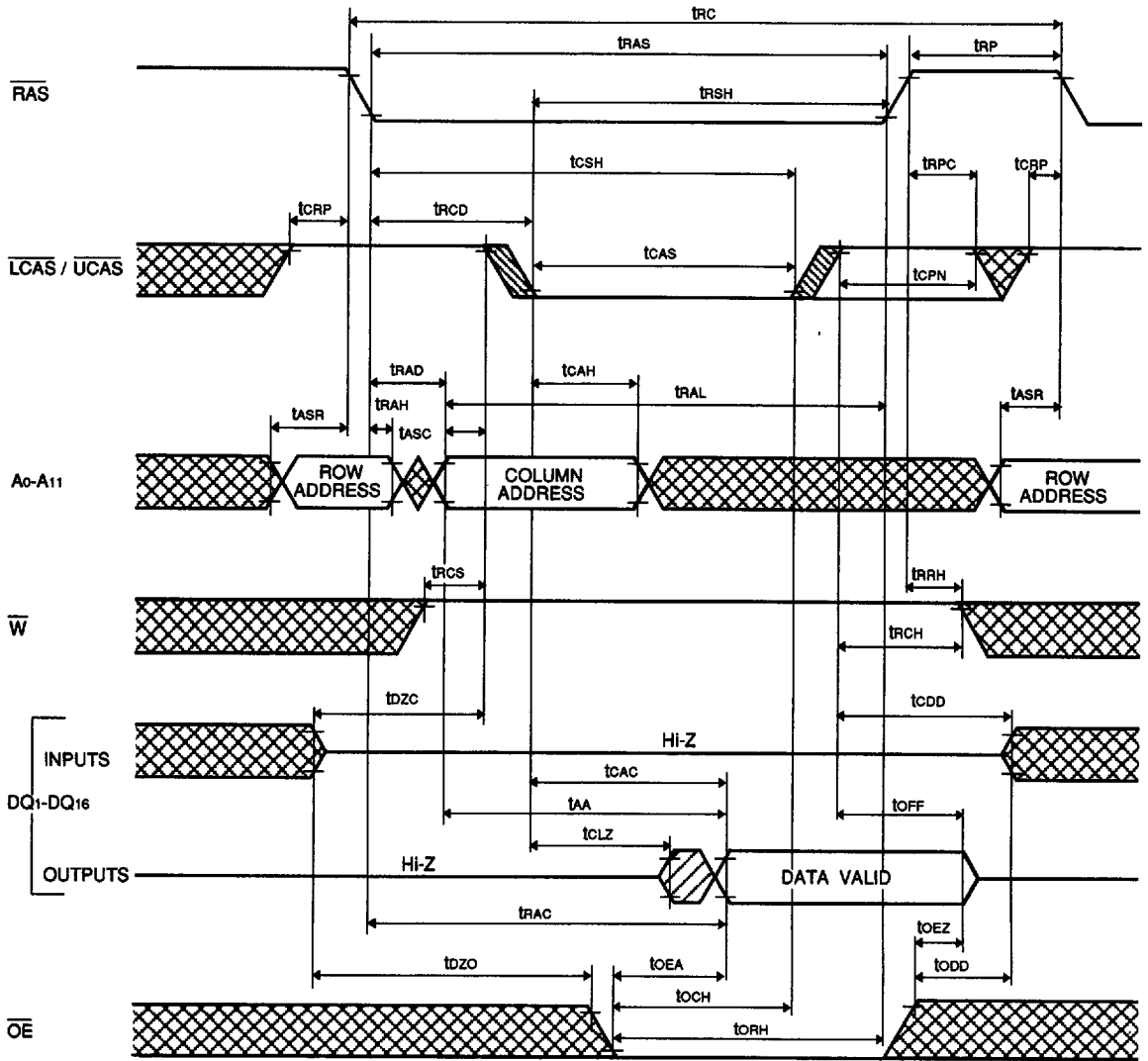
Symbol	Parameter	Limits						Unit
		M5M416160B-6,-6S		M5M416160B-7,-7S		M5M416160B-8,-8S		
		Min	Max	Min	Max	Min	Max	
tc $\overline{\text{SR}}$	$\overline{\text{CAS}}$ setup time before $\overline{\text{RAS}}$ low	10		10		10		ns
t $\overline{\text{CHR}}$	$\overline{\text{CAS}}$ hold time after $\overline{\text{RAS}}$ low	10		15		15		ns

Note 27: Eight or more $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ cycles instead of eight $\overline{\text{RAS}}$ cycles are necessary for proper operation of $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh mode.

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Timing Diagrams (Note 28) Read Cycle



Note 28



Indicates the don't care input.
 $V_{IH}(\min.) \leq V_{IN} \leq V_{IH}(\max.)$ or $V_{IL}(\min.) \leq V_{IN} \leq V_{IL}(\max.)$



Indicates the invalid output.

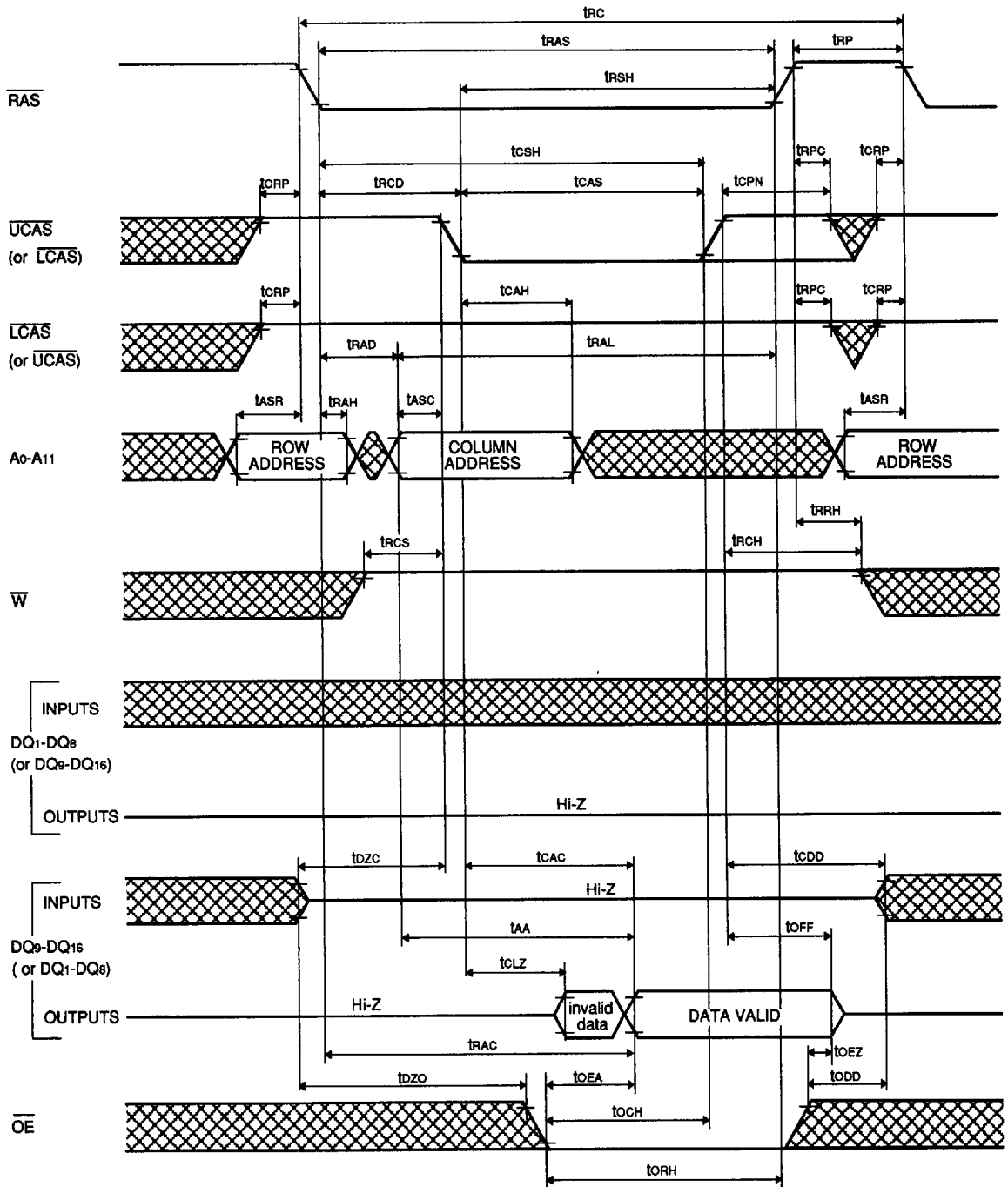


Indicates the skew of the two inputs.

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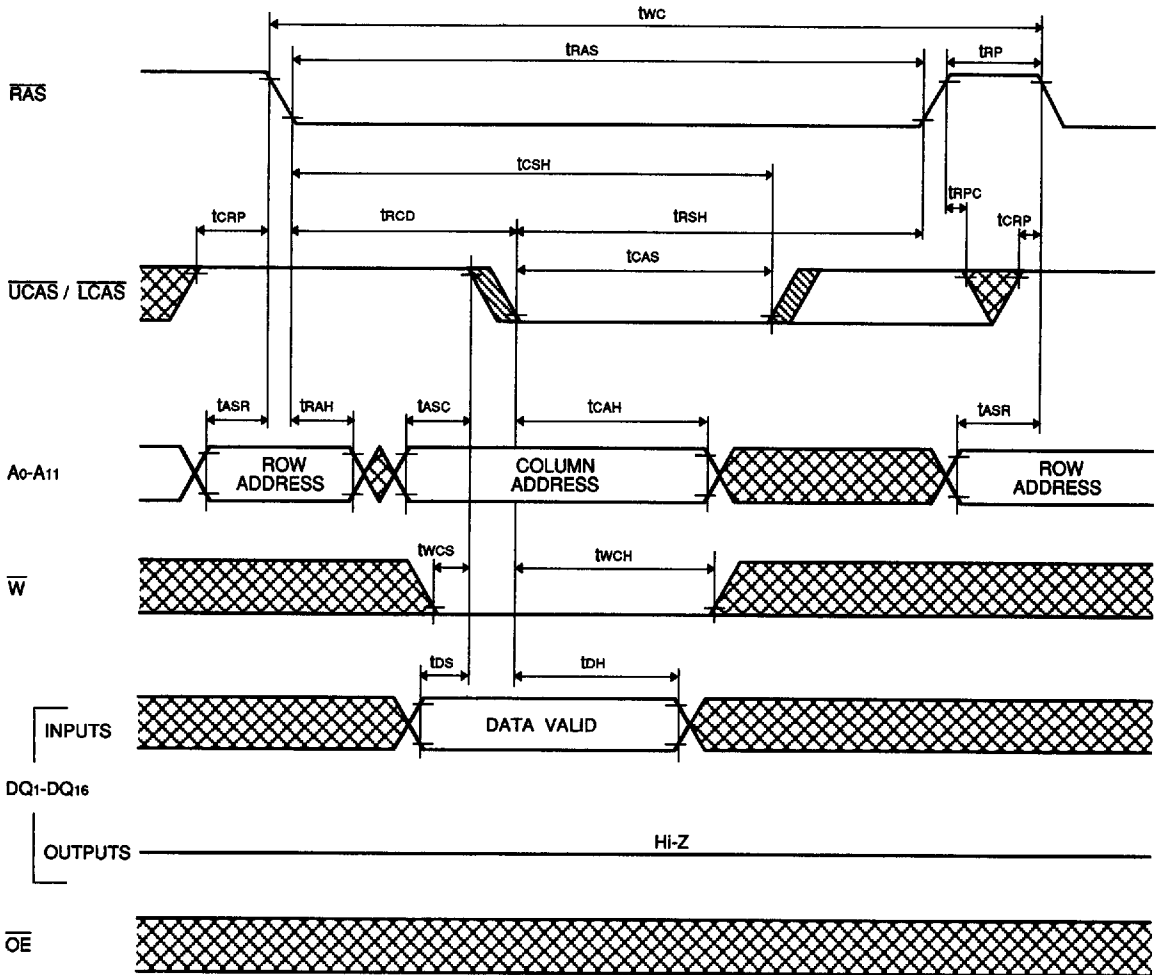
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Upper / (Lower) Byte Read Cycle



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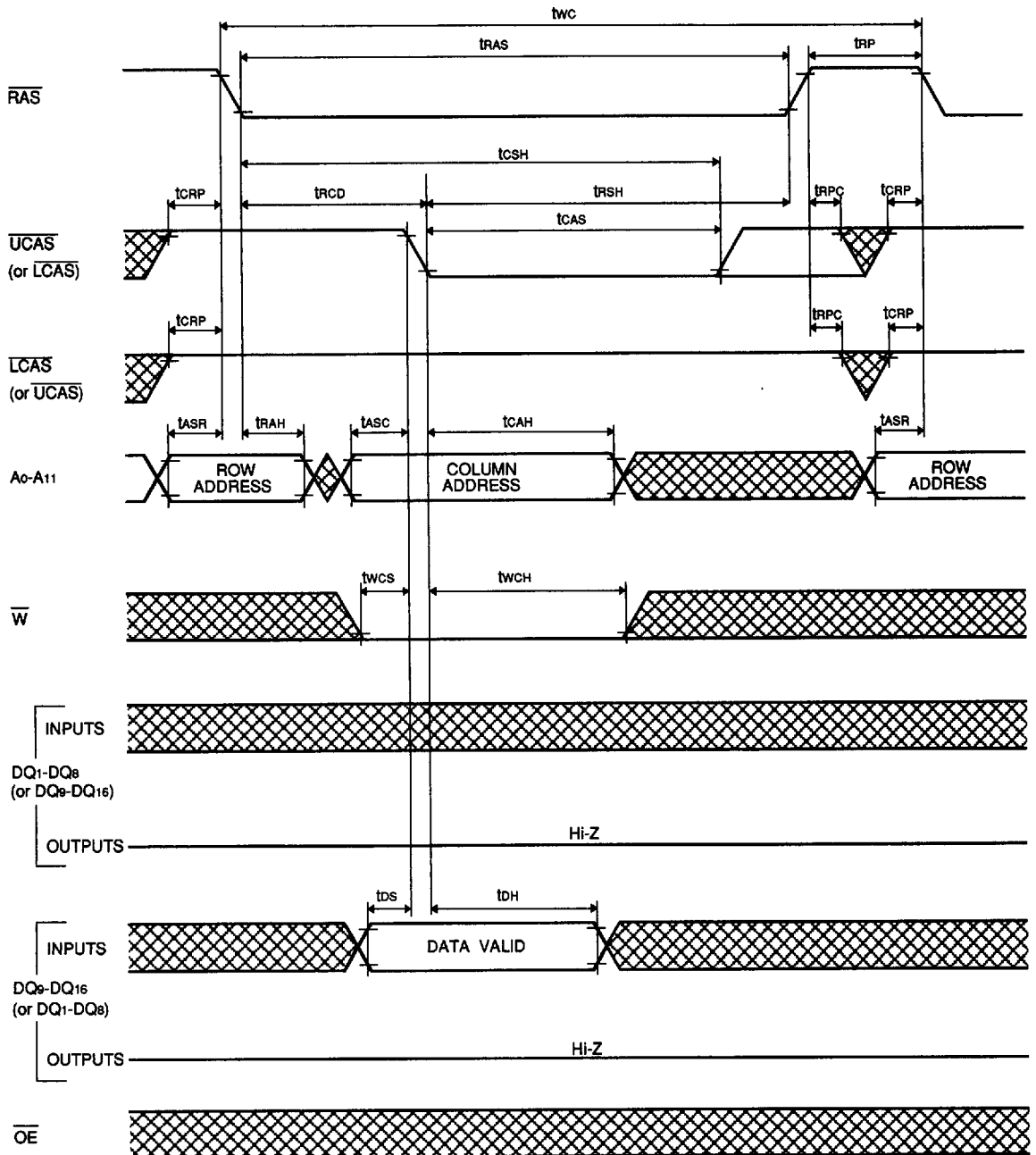
Write Cycle (Early write)



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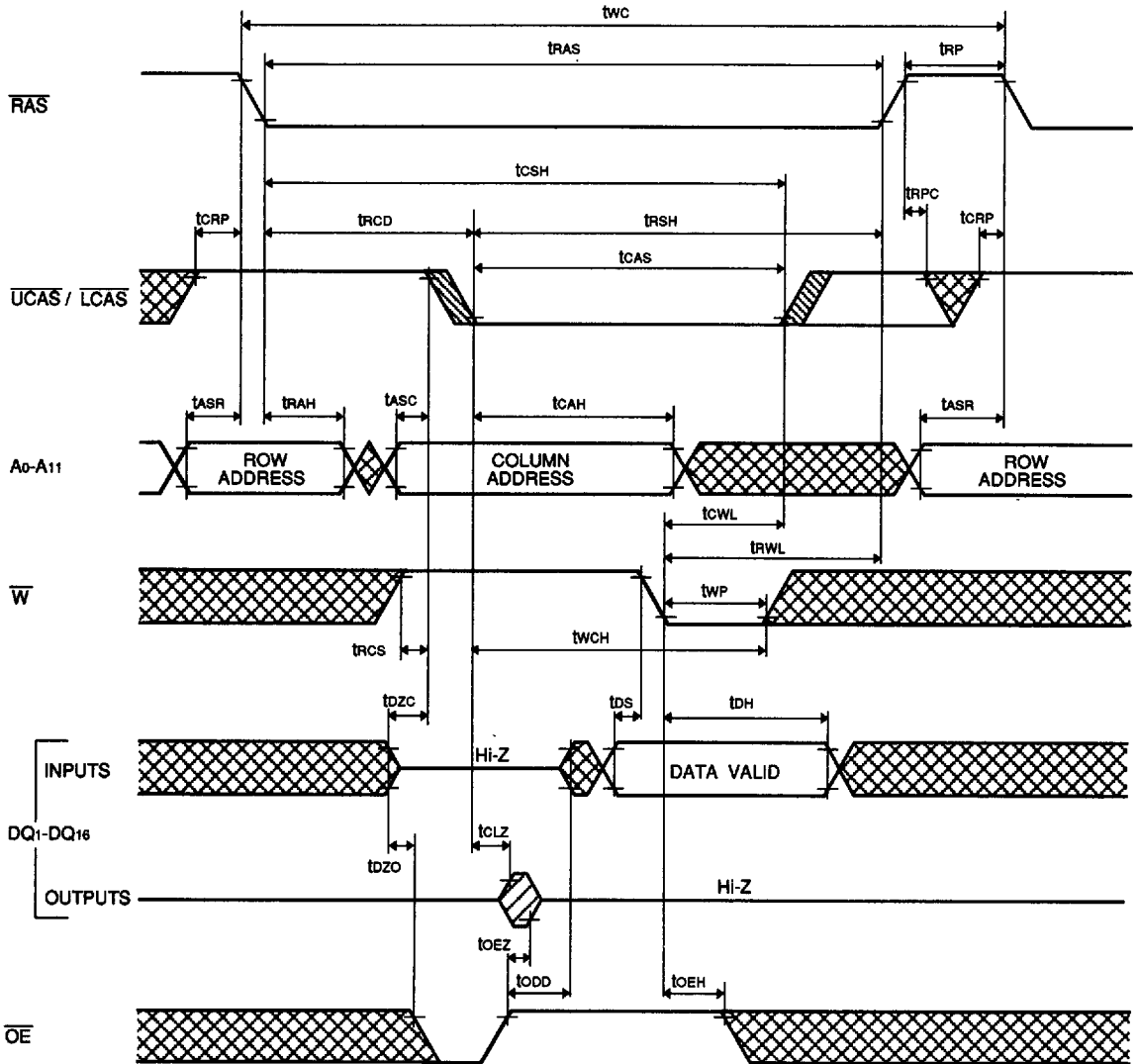
Upper/(Lower) Byte Write Cycle (Early write)



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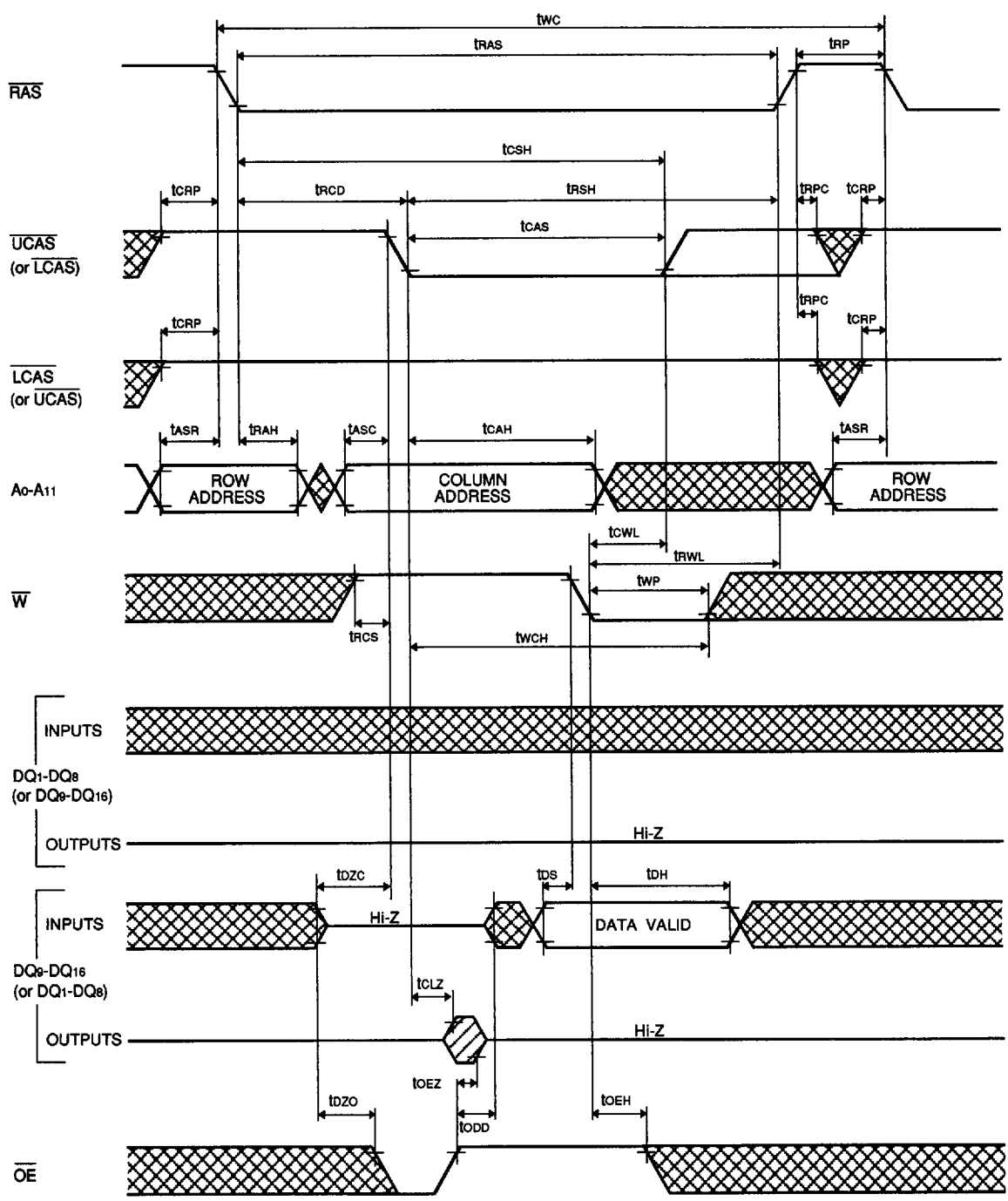
Write Cycle (Delayed write)



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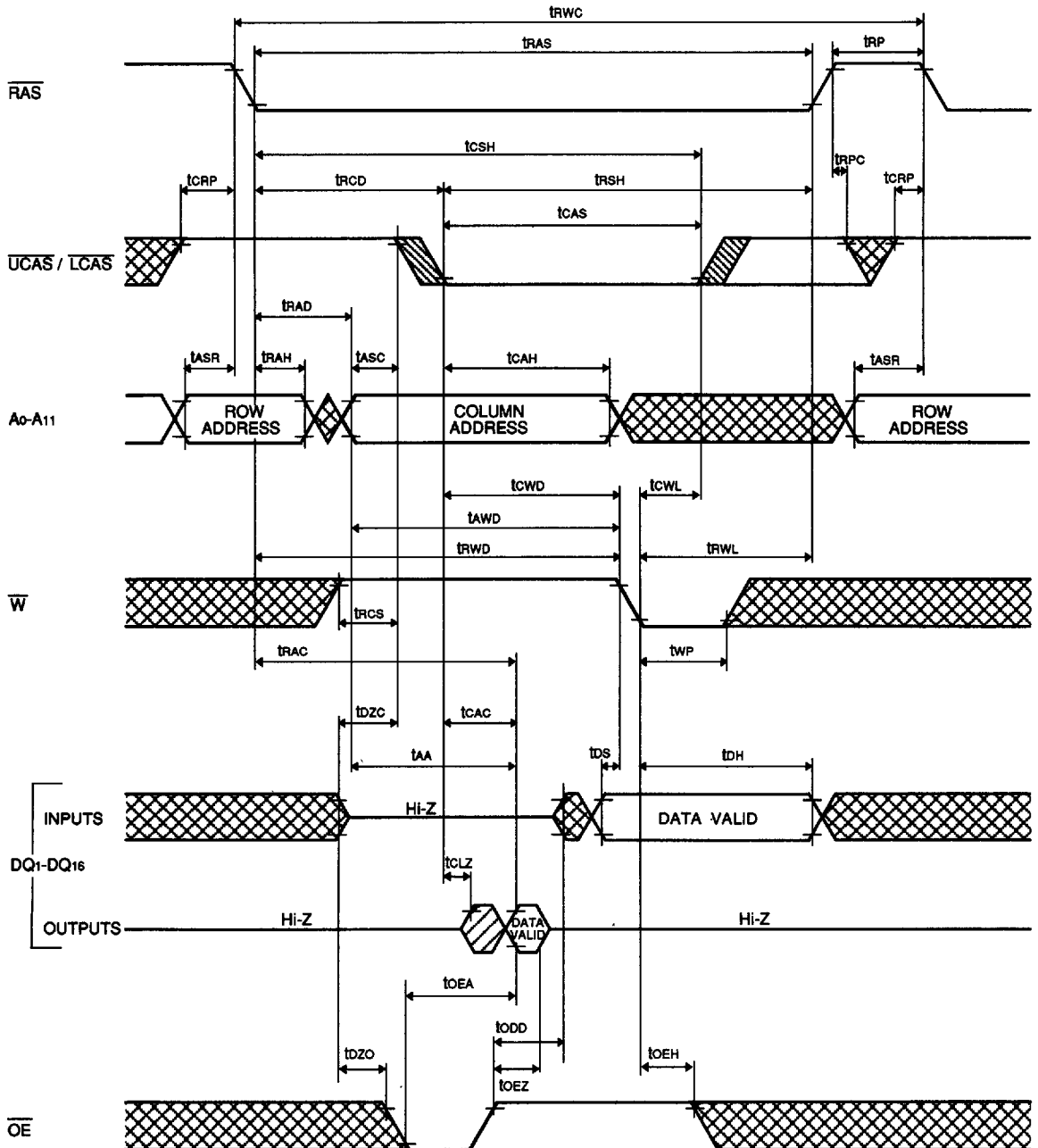
Upper/(Lower) Byte Write Cycle (Delayed write)



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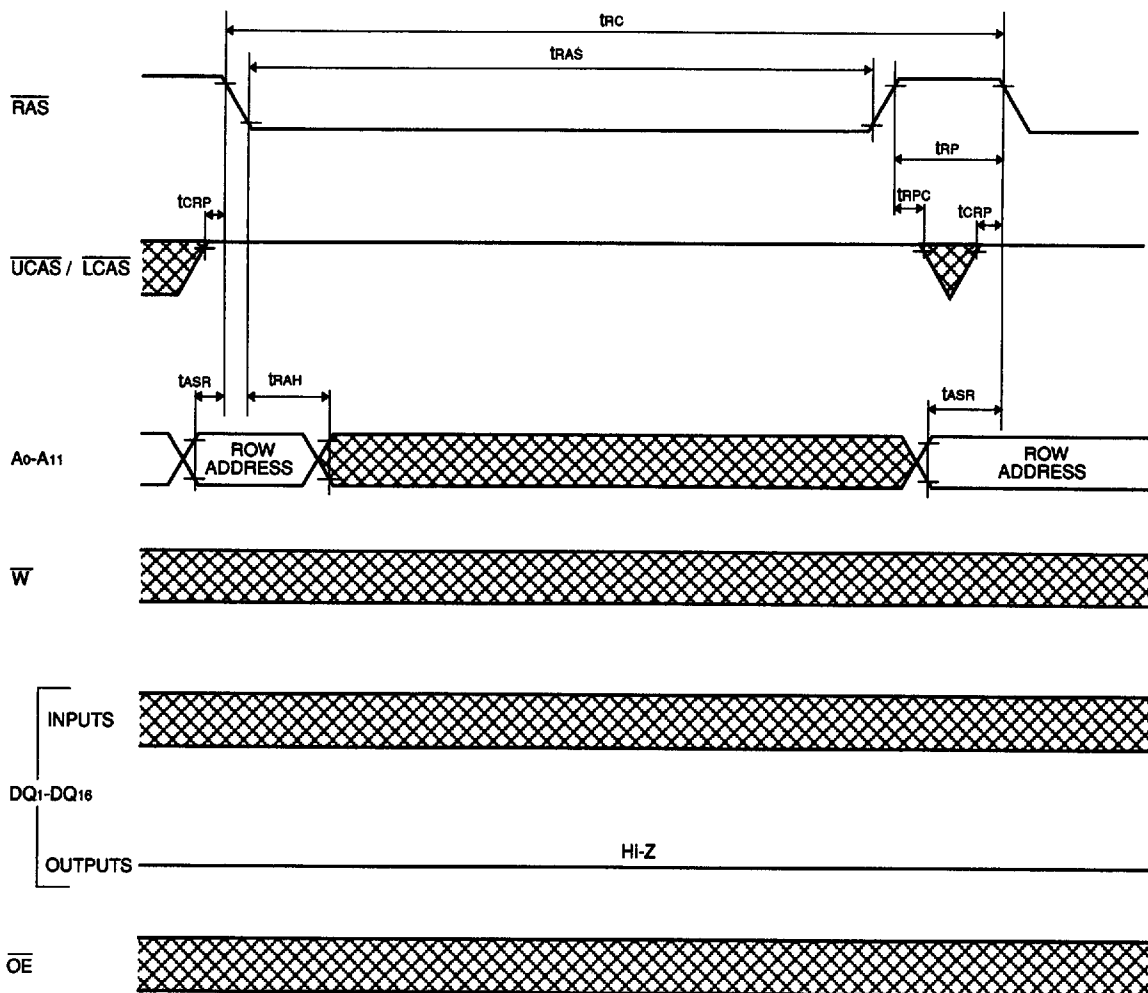
Read-Write, Read-Modify-Write Cycle



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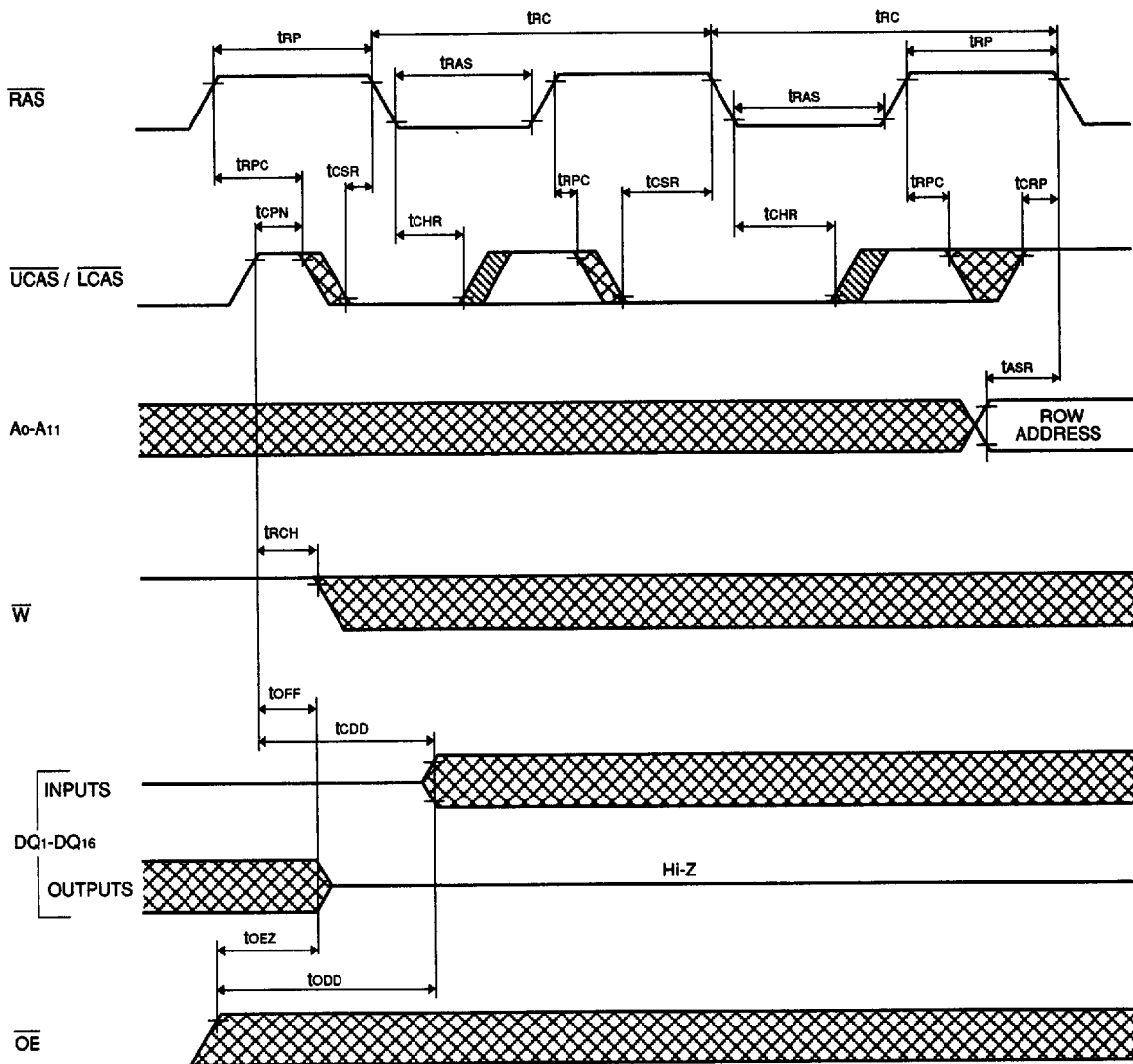
RAS-only Refresh Cycle



M5M416160BJ,TP,RT-6,-7,-8,-6S,-7S,-8S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

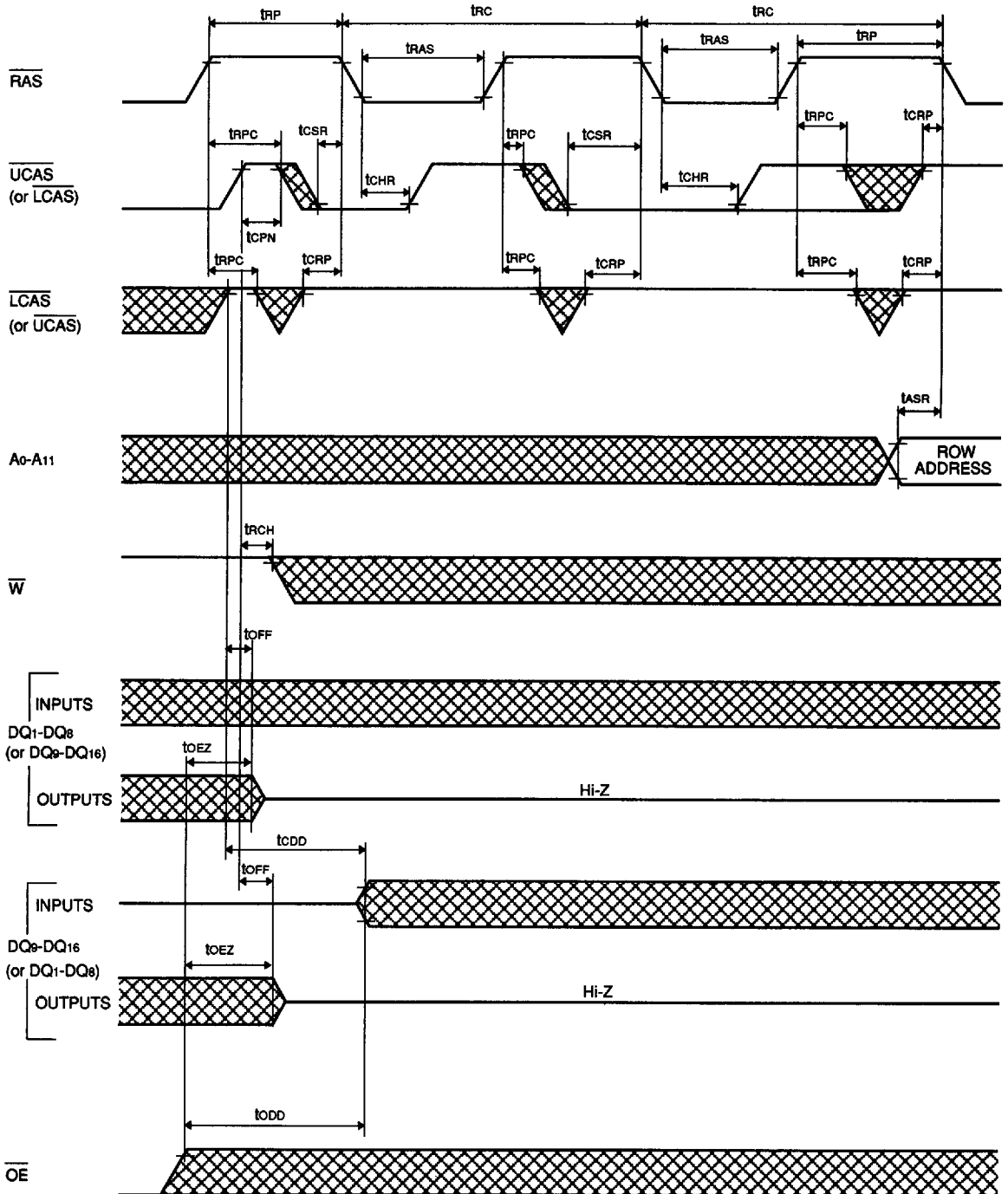
CAS before RAS Refresh Cycle



M5M416160BJ,TP,RT-6,-7,-8,-6S,-7S,-8S

FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

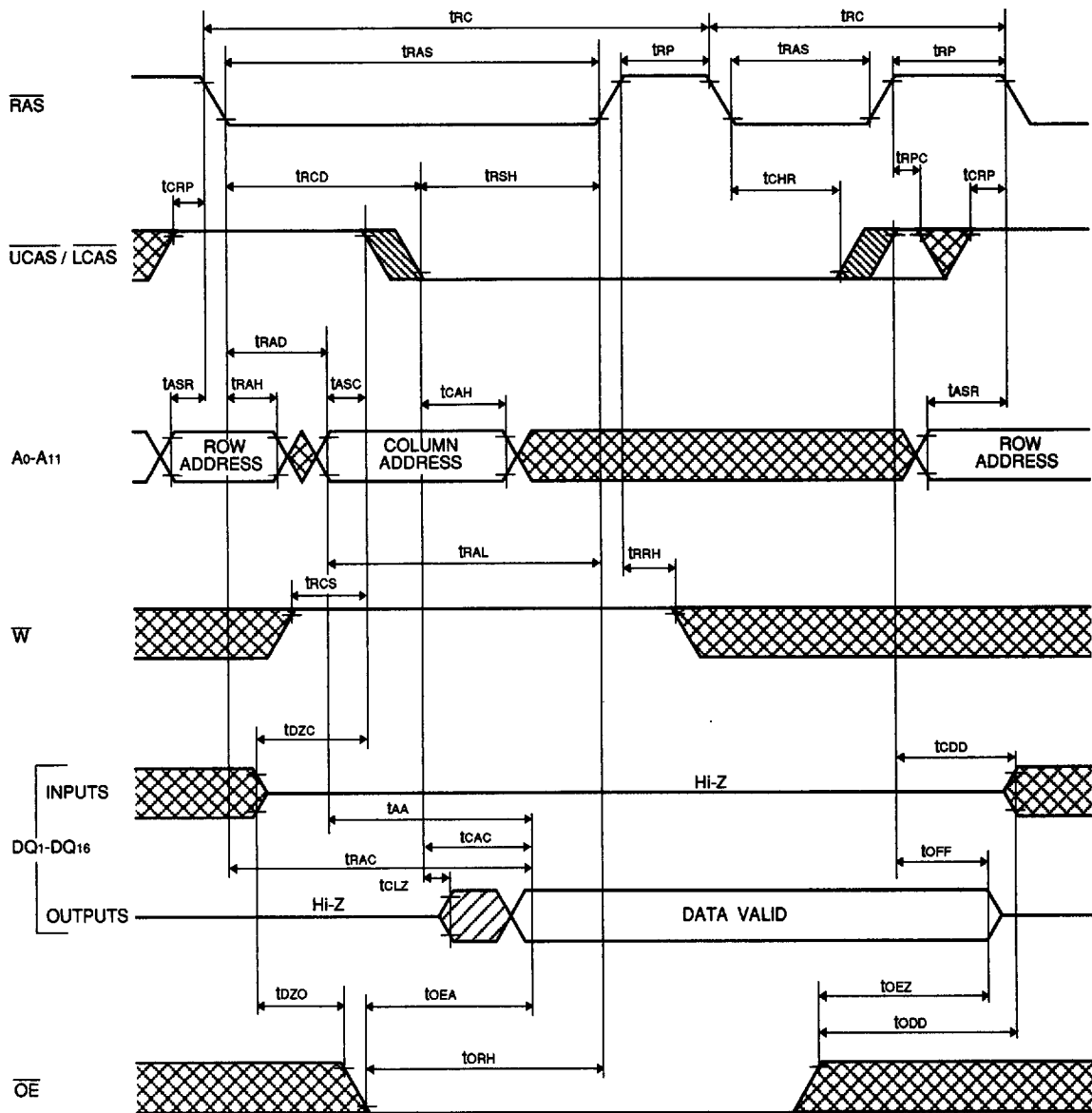
Upper/(Lower) CAS before RAS Refresh Cycle



M5M416160BJ,TP,RT-6,-7,-8,-6S,-7S,-8S

FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

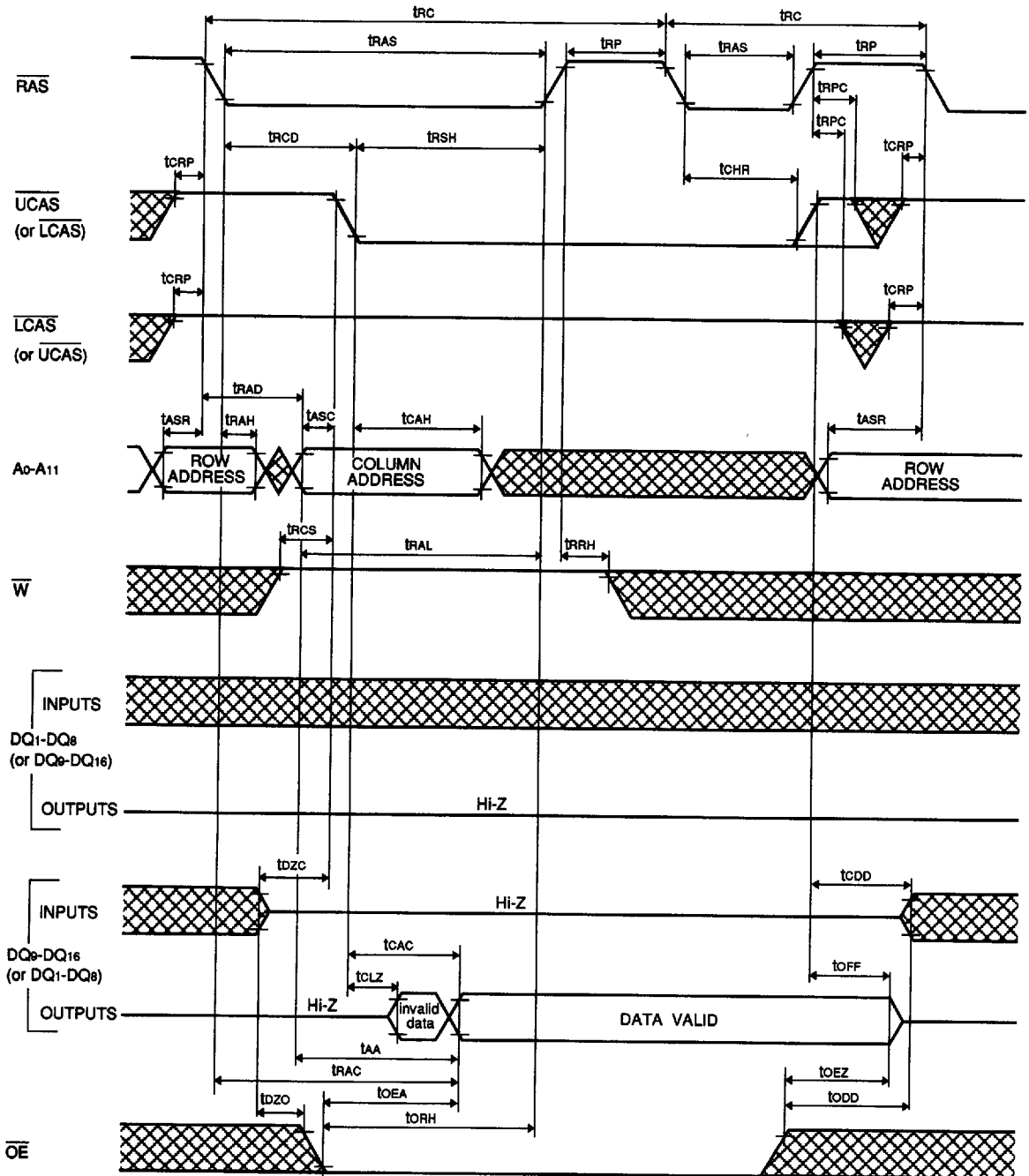
Hidden Refresh Cycle (Read) (Note 29)



Note 29: Early write, delayed write, read write or read modify write cycle is applicable instead of read cycle. Timing requirements and output state are the same as that of each cycle shown above.

FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

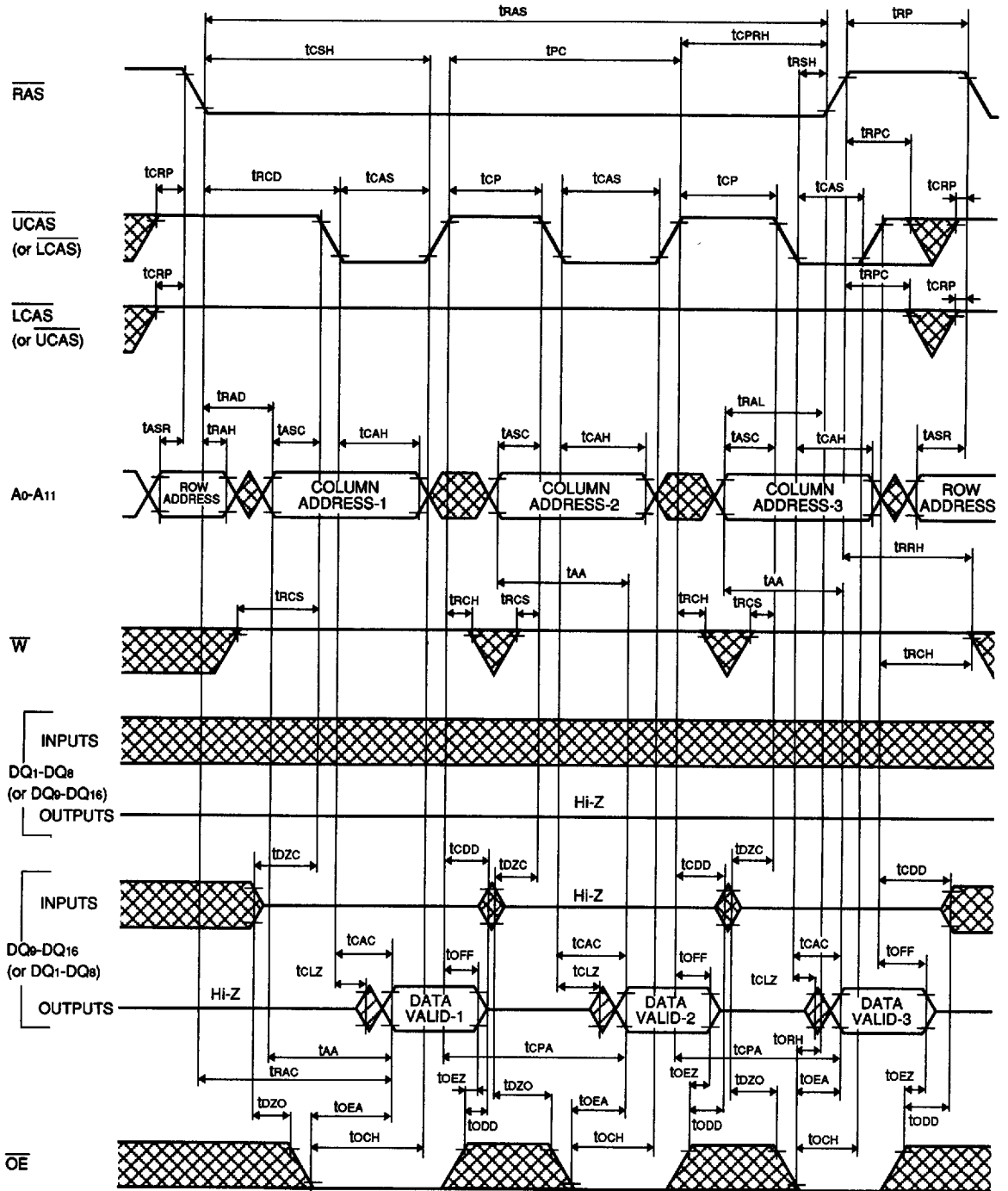
Upper/(Lower) Hidden Refresh Cycle (Byte Read) (Note 29)



Note 29: Early write, delayed write, read write or read modify write cycle is applicable instead of read cycle.
 Timing requirements and output state are the same as that of each cycle shown above.

FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

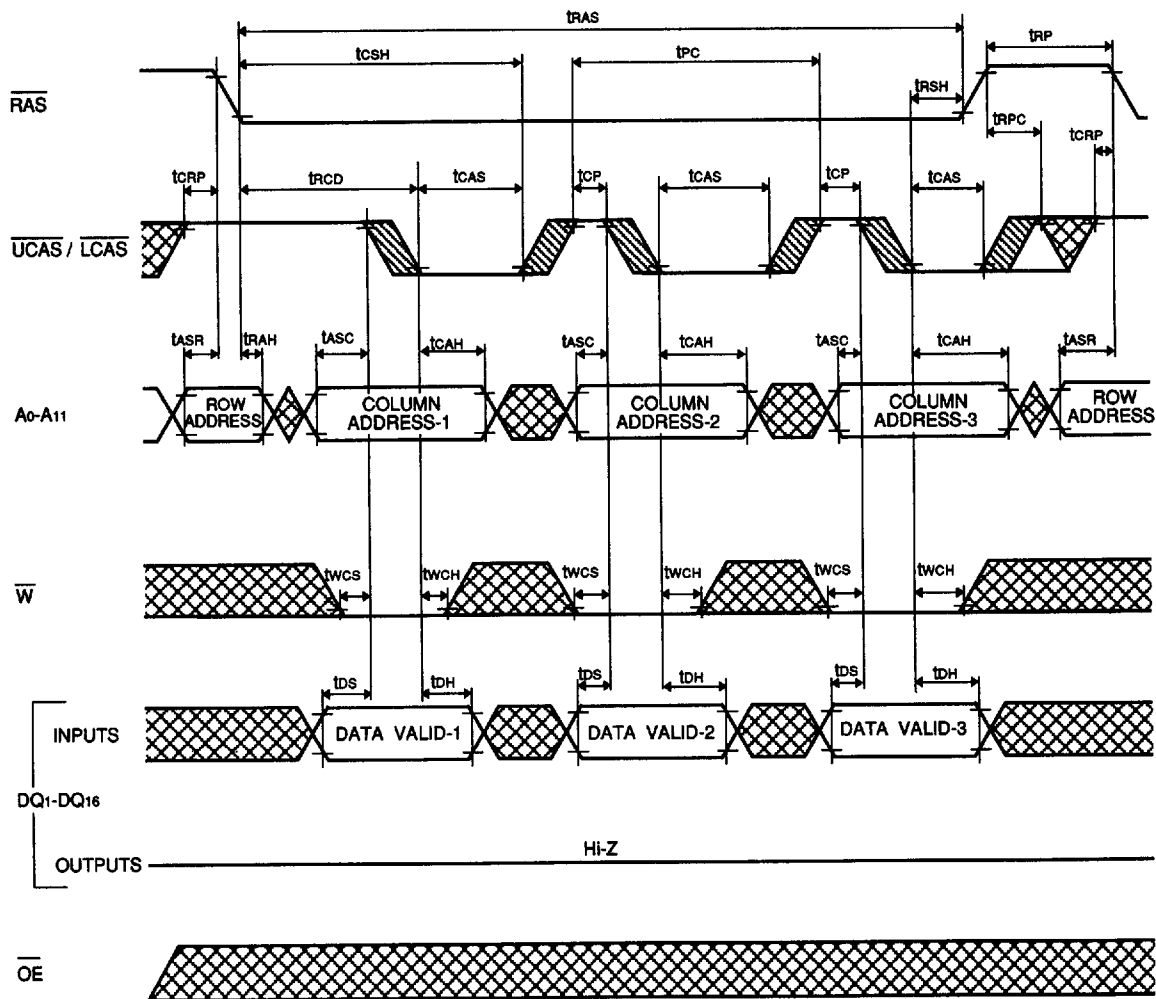
Upper/(Lower) Fast Page Mode Read Cycle



M5M416160BJ,TP,RT-6,-7,-8,-6S,-7S,-8S

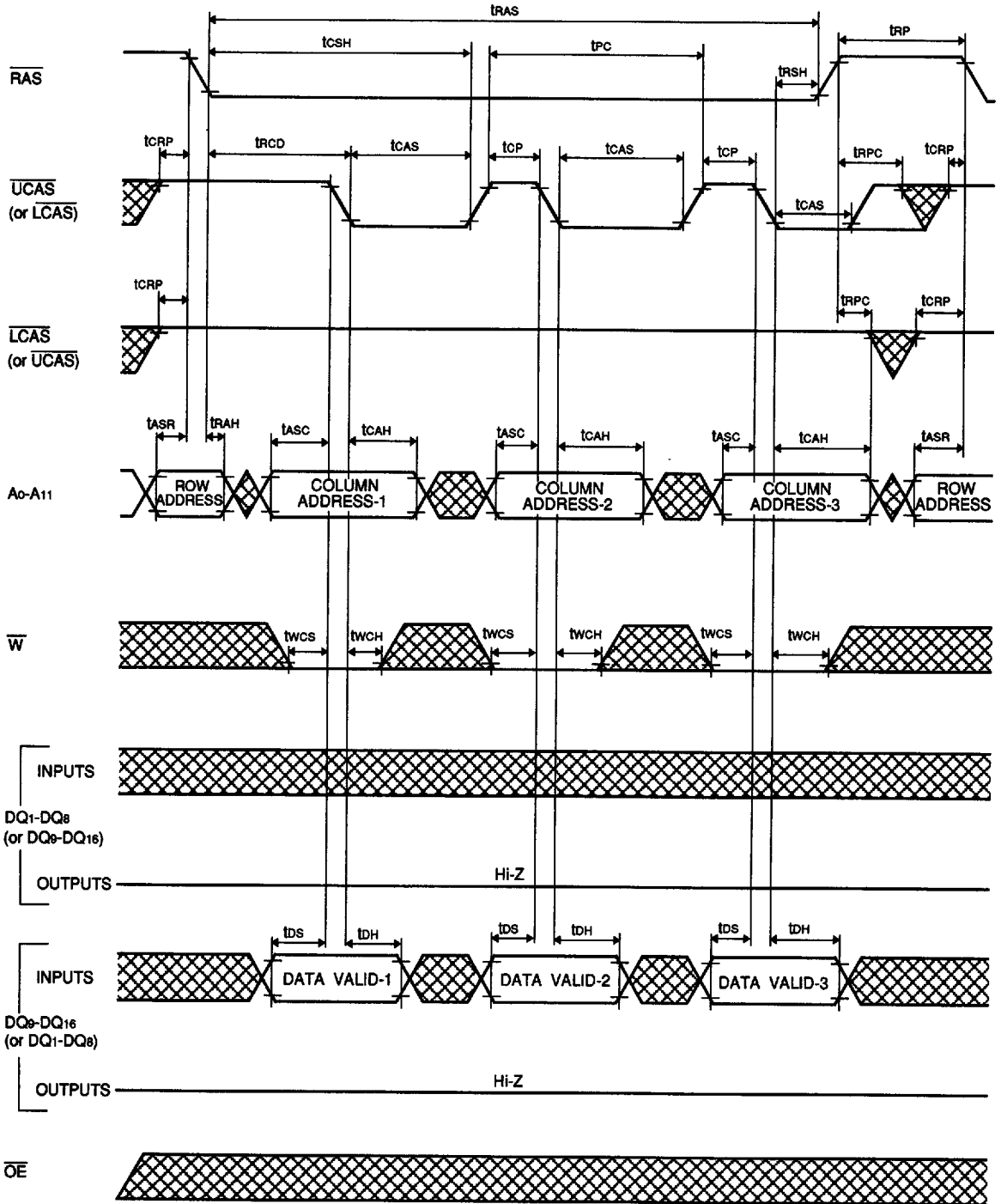
FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Write Cycle (Early Write)



FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

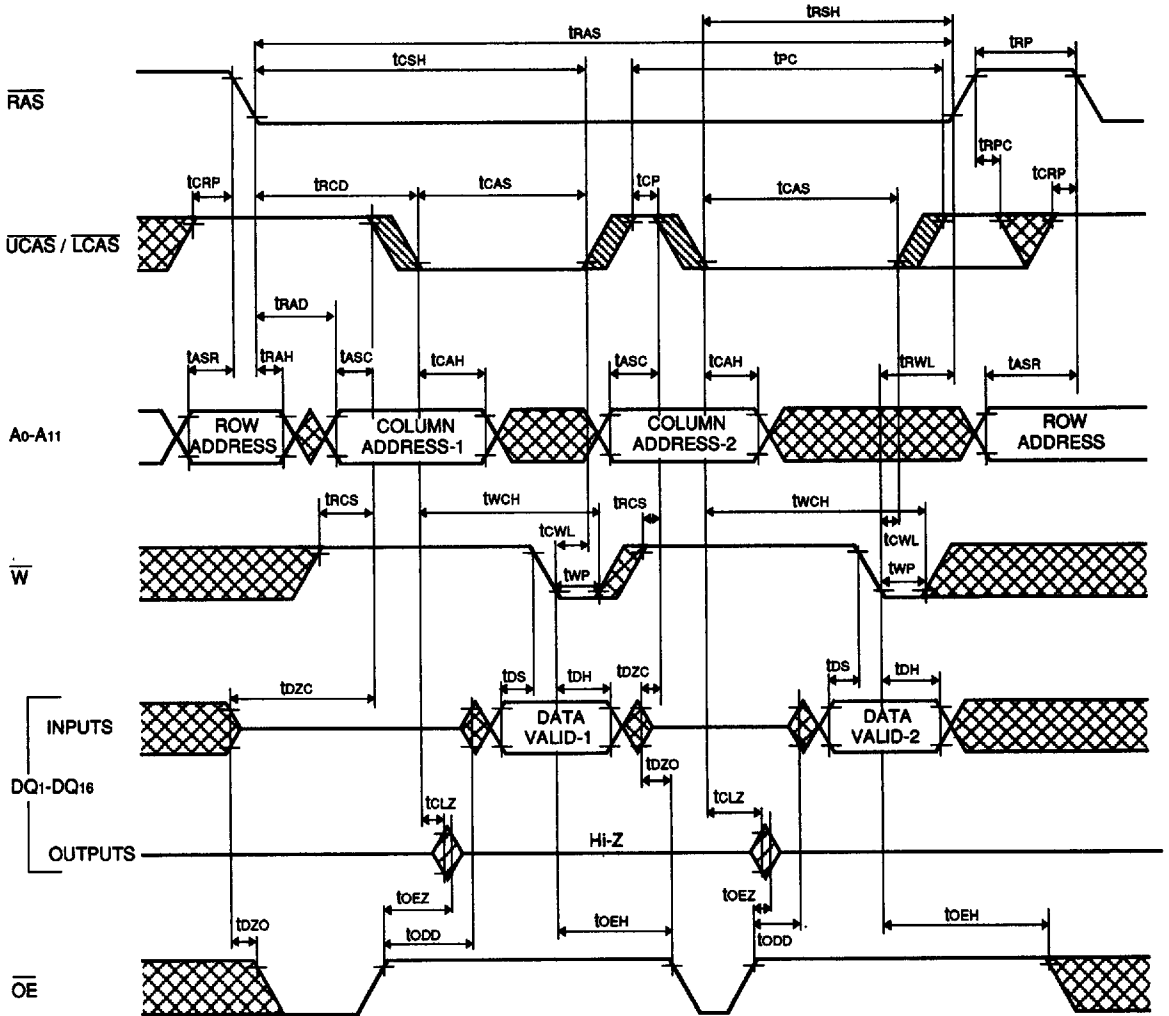
Fast Page Mode Upper/(Lower) Byte Write Cycle (Early Write)



M5M416160BJ, TP, RT-6, -7, -8, -6S, -7S, -8S

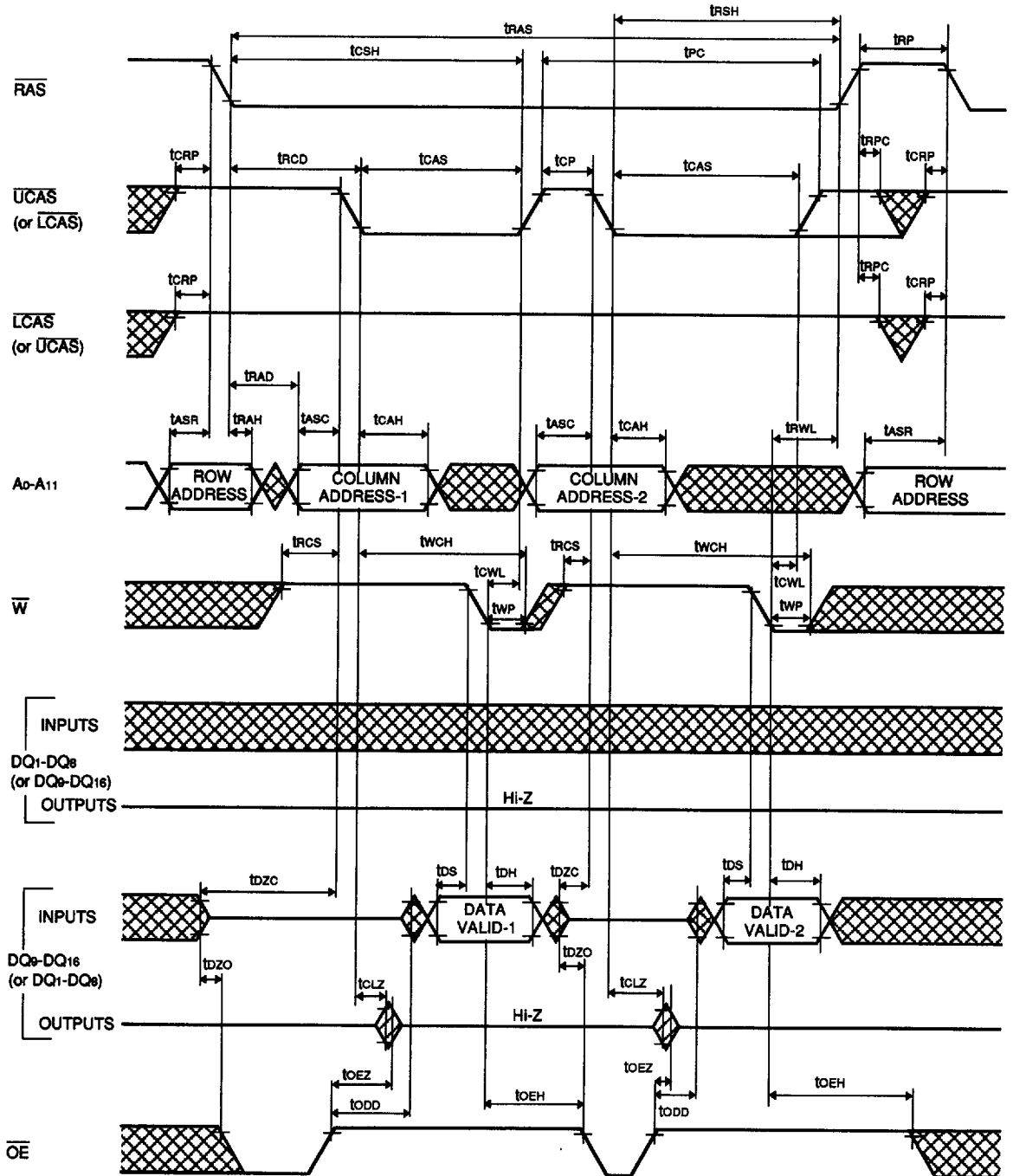
FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Write Cycle (Delayed Write)



FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

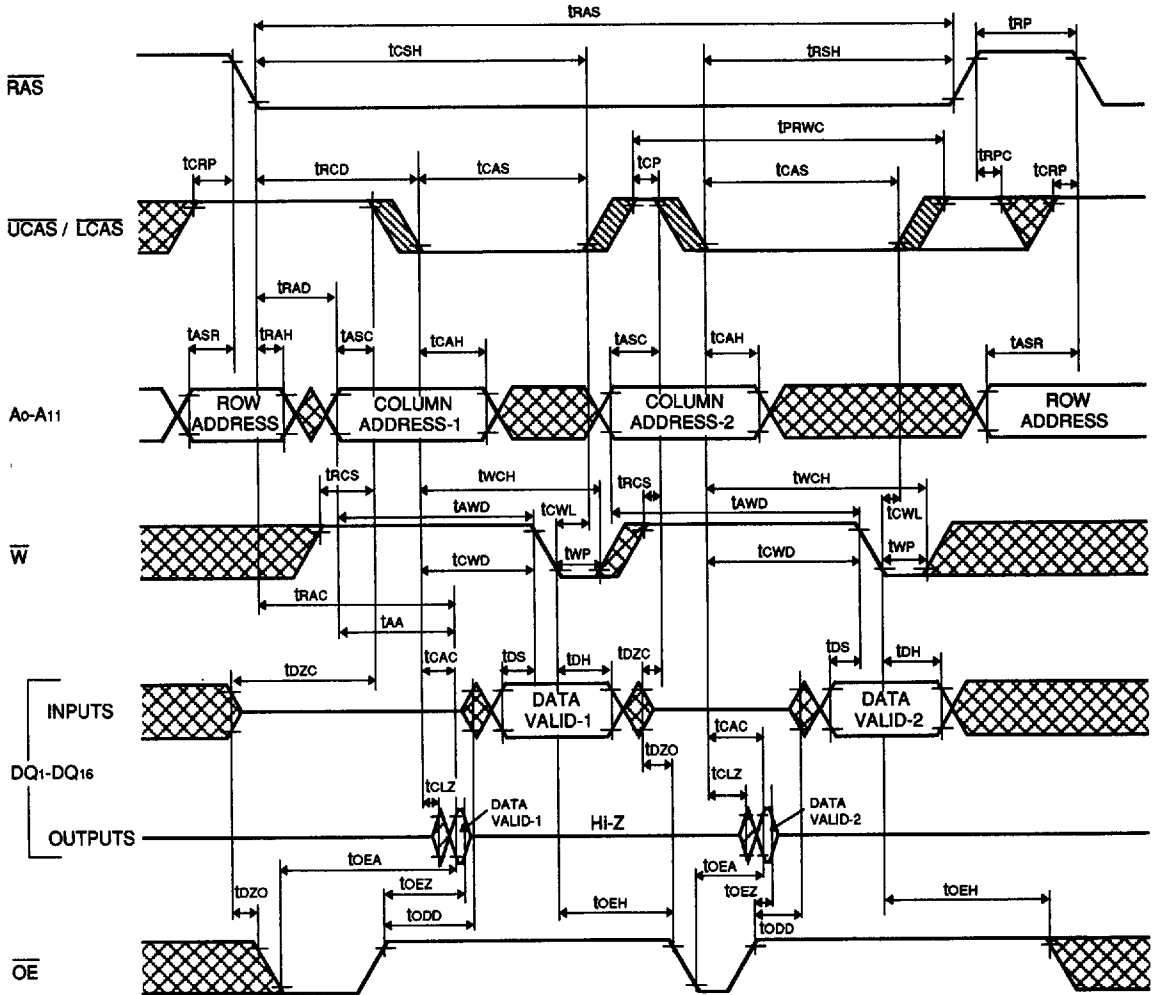
Fast Page Mode Upper / (Lower) Byte Write (Delayed Write)



M5M416160BJ,TP,RT-6,-7,-8,-6S,-7S,-8S

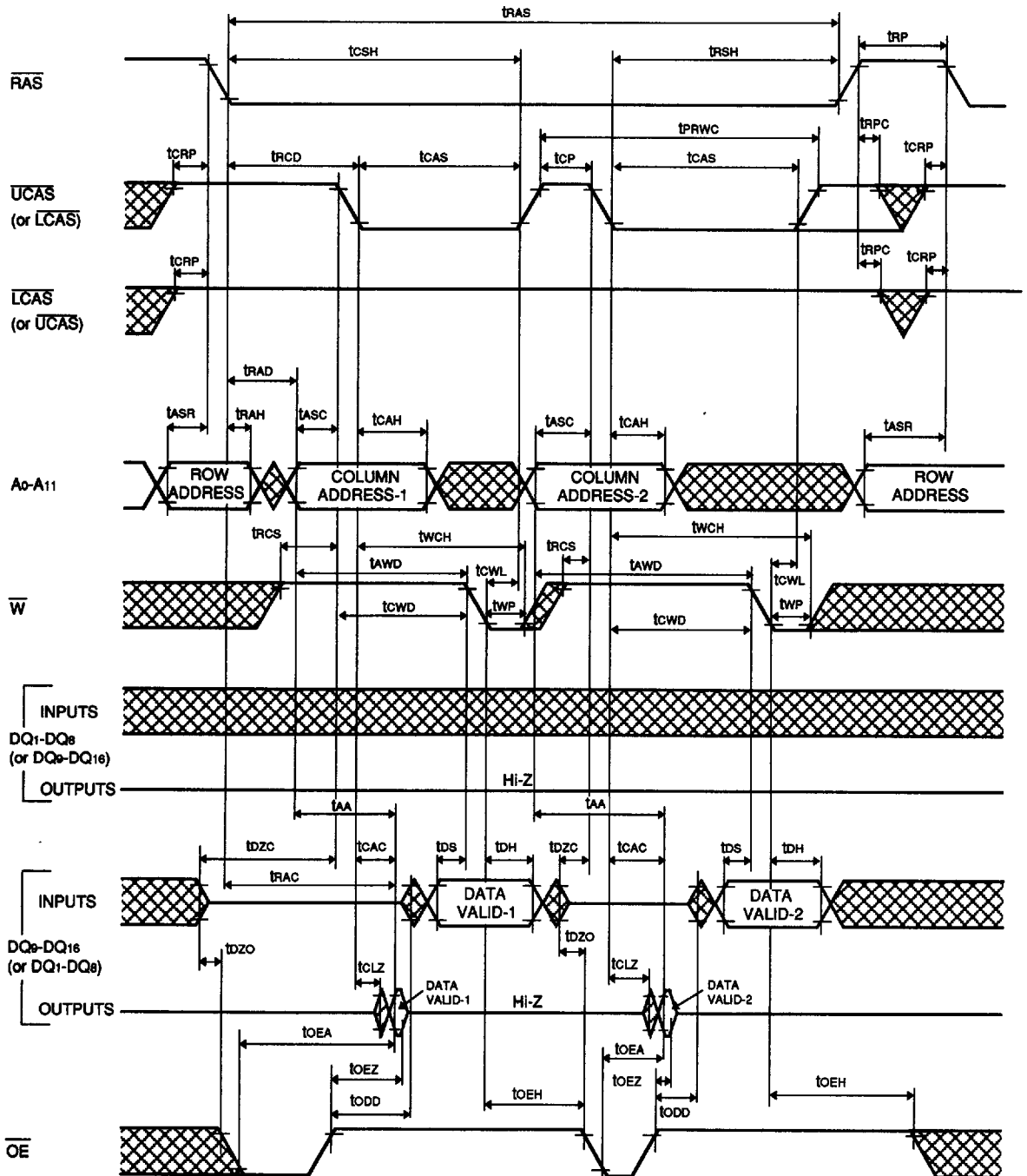
FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Read-Write, Read-Modify-Write Cycle



FAST PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Read-Upper/(Lower) Write, Read-Modify-Upper/(Lower) Write Cycle



M5M416160BJ,TP,RT-6,-7,-8,-6S,-7S,-8S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

SELF REFRESH SPECIFICATIONS

Self refresh devices are denoted by "S" after speed item, like -6S / -7S / -8S. The other characteristics and requirements than the below are same as normal devices.

ELECTRICAL CHARACTERISTICS (Ta=0~70°C, Vcc=5V ±10%, Vss=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
I _{CCA} (AV)	Average supply current from Vcc Self - Refresh cycle	M5M416160B -6S,-7S,-8S RAS = CAS ≤ 0.2V			400	μA

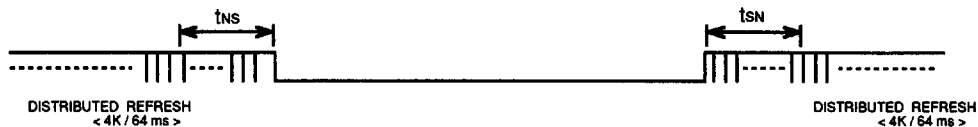
TIMING REQUIREMENTS (Ta=0~70°C, Vcc=5V ±10%, Vss=0V, unless otherwise noted See notes 13,14)

Symbol	Parameter	Limits						Unit
		M5M416160B-6S		M5M416160B-7S		M5M416160B-8S		
		Min	Max	Min	Max	Min	Max	
t _{RAS}	Self Refresh RAS low pulse width	100		100		100		μs
t _{RPS}	Self Refresh RAS high precharge time	90		110		130		ns
t _{CHS}	Self Refresh RAS hold time	- 50		- 50		- 50		ns

SELF REFRESH ENTRY & EXIT CONDITIONS

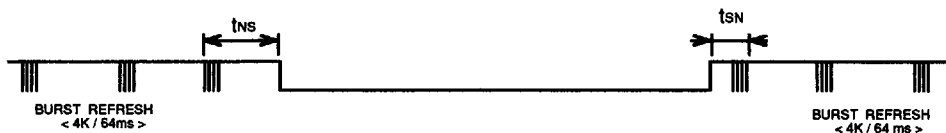
- (1) In case of distributed refresh

The last / first full refresh cycles (4K) must be made within t_{NS} / t_{SN} before / after self refresh , on the condition of t_{NS} ≤ 64 ms and t_{SN} ≤ 64 ms.



- (2) In case of burst refresh

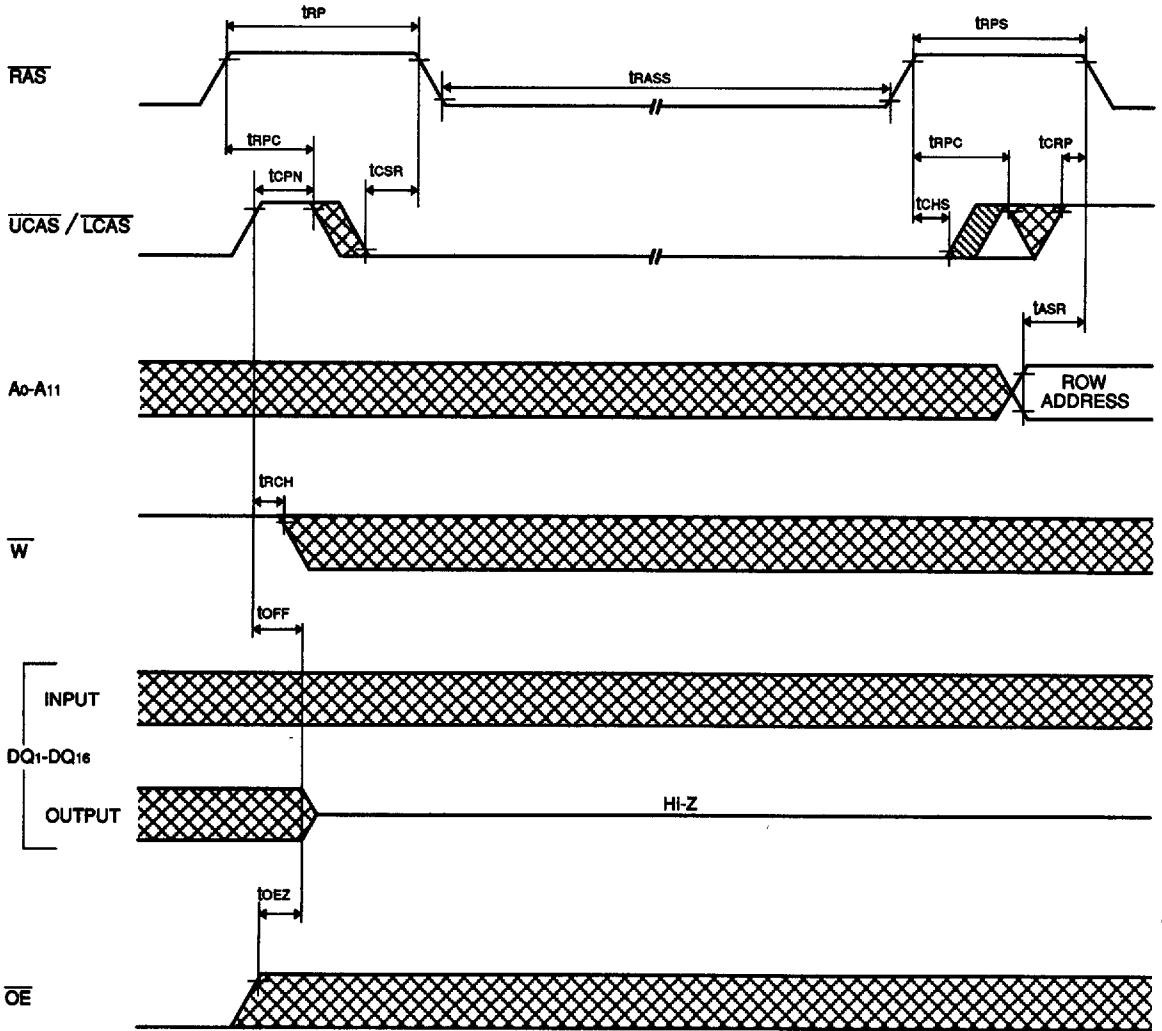
The last / first full refresh cycles (4K) must be made within t_{NS} / t_{SN} before / after self refresh , on the condition of t_{NS} + t_{SN} ≤ 64 ms.



M5M416160BJ, TP, RT-6, -7, -8, -6S, -7S, -8S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Self Refresh Cycle



FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper/(Lower) Self Refresh Cycle*

